

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	292	(34/380).CCLS.	USPAT	OR	OFF	2005/09/04 21:55
S2	0	("methodandeliminatingadjmoisture and(semiconductorsubstrate)").PN.	USPAT	OR	OFF	2005/09/04 21:56
S3	1437	(wafer semiconductor substrate electronic adj component\$1) and moisture and (remov\$3 eliminat\$3) and method and warm and dry and storage	USPAT	OR	OFF	2005/09/04 21:58
S4	149	(wafer semiconductor substrate electronic adj component\$1) and moisture and (remov\$3 eliminat\$3) and method and (warm dry) adj atmosphere and storage	USPAT	OR	OFF	2005/09/04 22:00
S5	157	(34/389).CCLS.	USPAT	OR	OFF	2005/09/04 22:00
S6	177	(34/444).CCLS.	USPAT	OR	OFF	2005/09/04 22:02
S7	63	(34/445).CCLS.	USPAT	OR	OFF	2005/09/04 22:07
S8	158	(34/446).CCLS.	USPAT	OR	OFF	2005/09/04 22:09
S9	104	(34/467).CCLS.	USPAT	OR	OFF	2005/09/04 22:12
S10	61	(34/474).CCLS.	USPAT	OR	OFF	2005/09/04 22:14
S11	74	(34/475).CCLS.	USPAT	OR	OFF	2005/09/04 22:18
S12	28	(34/476).CCLS.	USPAT	OR	OFF	2005/09/04 22:23
S13	29	(34/477).CCLS.	USPAT	OR	OFF	2005/09/04 22:26
S14	107	(34/493).CCLS.	USPAT	OR	OFF	2005/09/04 22:28
S15	62	(34/494).CCLS.	USPAT	OR	OFF	2005/09/04 22:36
S16	68	(34/192).CCLS.	USPAT	OR	OFF	2005/09/04 22:38
S17	106	(34/195).CCLS.	USPAT	OR	OFF	2005/09/04 22:41
S18	271	(34/197).CCLS.	USPAT	OR	OFF	2005/09/04 22:46
S19	308	(34/201).CCLS.	USPAT	OR	OFF	2005/09/04 22:48
S20	291	(34/202).CCLS.	USPAT	OR	OFF	2005/09/04 22:53
S21	175	(34/211).CCLS.	USPAT	OR	OFF	2005/09/04 22:56
S22	216	(34/212).CCLS.	USPAT	OR	OFF	2005/09/04 22:58
S23	297	(34/218).CCLS.	USPAT	OR	OFF	2005/09/04 23:04
S24	541	(62/78).CCLS.	USPAT	OR	OFF	2005/09/04 23:12
S25	0	(165/47.T).CCLS.	USPAT	OR	OFF	2005/09/04 23:15
S26	0	(165/47T).CCLS.	USPAT	OR	OFF	2005/09/04 23:15
S27	575	(312/31).CCLS.	USPAT	OR	OFF	2005/09/04 23:15
S28	0	("312.31.01").PN.	USPAT	OR	OFF	2005/09/04 23:20